



## EC Declaration of Conformity (DoC)

**We**

Texas Instruments Incorporated  
 12500 TI Boulevard  
 Dallas, Texas 75243 USA

**Declare that the DoC is issued under our sole responsibility and belongs to the following product(s):**

<b>Product Type:</b>	CC2564MODA Bluetooth® Host Controller Interface (HCI) Module
<b>Equipment Name:</b>	CC2564 Bluetooth HCI Module
<b>Model Number:</b>	CC2564MODA
<b>SW Version:</b>	6.7.16

**The object of the declaration described above is in conformity with the relevant Union harmonization legislation:**

Radio Equipment Directive 2014/53/EU  
 RoHS2 Directive 2011/65/EU

**The following harmonized standards and technical specifications have been applied:**

EN 301489-1 V2.1.1	ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 1: Common technical requirements; Harmonised Standard covering the essential requirements of article 3.1(b) of the Directive 2014/53/EU and the essential requirements of article 6 of the Directive 2014/30/EU;
EN 301489-17 V3.1.1	ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 17: Specific conditions for Broadband Data Transmission Systems; Harmonised Standard covering the essential requirements of article 3.1(b) of Directive 2014/53/EU
EN 300328 v2.1.1	Wideband transmission systems; Data transmission equipment operating in the 2,4 GHz ISM band and using wide band modulation techniques; Harmonised Standard covering the essential requirements of article 3.2 of Directive 2014/53/EU
EN 62479:2010	Assessment of the compliance of low power electronic and electrical equipment with the basic restrictions related to human exposure to



	electromagnetic fields (0 Hz - 300 GHz)
EN 60950-1:2006+A11:2009+A1:2010+A12:2011+A2:2013	Information technology equipment – Safety-Part 1: General requirements
EN 50581:2012	Technical documentation for the assessment of electrical and electronic products with respect to the restrictions of hazardous substances

**Notified Body:**

<b>Notified Body:</b>	CTC advanced
<b>Notified Body Number</b>	0682
<b>Reference number of the certificate of notified body</b>	T818151E-01-TEC

**Technical Compliance File Held by:**

Texas Instruments Incorporated  
 12500 TI Boulevard  
 Dallas, Texas 75243 USA

**Signed for and on behalf of Texas Instruments Incorporated**

<b>Name:</b>	Mattias Lange, General Manager
<b>Address:</b>	12500 TI Boulevard, Dallas, Texas, 75243

Dallas

Place of issue

8/30/17

Date of issue

Signature of Authorized Person

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